

Global Silicon Carbide Wafer Laser Slicing Equipment Supply, Demand and Key Producers, 2026-2032

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Abstracts

The global Silicon Carbide Wafer Laser Slicing Equipment market size is expected to reach \$ 831 million by 2032, rising at a market growth of 9.8% CAGR during the forecast period (2026-2032).

Silicon Carbide Wafer Laser Slicing Equipment refers to advanced semiconductor material processing systems used to cut, thin, and slice silicon carbide (SiC) wafers or ingots using laser-based or laser-assisted precision separation technologies. The equipment is mainly used in power semiconductor manufacturing, including SiC MOSFETs, SiC Schottky diodes, and high-voltage power devices. It enables high-precision wafer dicing, kerf minimization, low thermal damage, and improved wafer utilization compared with mechanical sawing methods. Main product forms include laser stealth dicing systems, laser grooving and cleaving systems, wafer thinning and slicing platforms, hybrid laser-mechanical slicing systems, and high-precision SiC wafer dicing equipment. This category excludes traditional mechanical dicing saws, plasma dicing systems, full wafer fabrication tools, and semiconductor device manufacturing services. The industrial chain of Silicon Carbide Wafer Laser Slicing Equipment includes upstream suppliers of ultrafast lasers (picosecond/femtosecond lasers), beam delivery optics, galvanometer scanning systems, precision motion stages, wafer handling robots, AI alignment systems, optical lenses, cooling systems, control software, sensors, and SiC wafer materials. Midstream manufacturers integrate laser sources, beam shaping modules, wafer positioning systems, slicing control algorithms, thermal management systems, and automation into complete SiC wafer laser slicing equipment. Downstream applications include SiC power device manufacturers, automotive semiconductor companies, renewable energy inverter manufacturers, EV powertrain suppliers, industrial power electronics producers, and advanced semiconductor fabs. Supporting services include process development, equipment calibration, wafer yield optimization,

maintenance, spare parts supply, installation, operator training, and lifecycle technical support. In 2025, global Silicon Carbide Wafer Laser Slicing Equipment production reached approximately 210 units, with an average global market price of around US\$1,600,000 per unit. The gross profit margin of major companies in the industry is between 30%-55%. In 2025, the global production capacity of silicon carbide wafer laser slicing equipment was approximately 300 units.

The Silicon Carbide Wafer Laser Slicing Equipment market is driven by the rapid expansion of silicon carbide power semiconductors used in electric vehicles, renewable energy systems, and high-efficiency power electronics. SiC wafers are extremely hard and brittle, making traditional mechanical dicing inefficient and prone to defects such as chipping and micro-cracks. Laser slicing technologies, including stealth dicing and ultrafast laser ablation, enable high-precision, low-damage wafer separation and significantly improve yield and device reliability. Manufacturers are focusing on improving laser pulse control, beam shaping accuracy, multi-layer processing capability, wafer throughput, and automation integration. As SiC wafer sizes increase from 6-inch to 8-inch and beyond, demand for high-precision laser slicing equipment continues to grow. However, the market remains specialized and capital-intensive, with adoption concentrated among leading SiC device manufacturers and advanced semiconductor fabs. Overall, the market is expected to grow steadily with the expansion of wide-bandgap semiconductor applications.

This report studies the global Silicon Carbide Wafer Laser Slicing Equipment production, demand, key manufacturers, and key regions.

This report is a detailed and comprehensive analysis of the world market for Silicon Carbide Wafer Laser Slicing Equipment and provides market size (US\$ million) and Year-over-Year (YoY) Growth, considering 2025 as the base year. This report explores demand trends and competition, as well as details the characteristics of Silicon Carbide Wafer Laser Slicing Equipment that contribute to its increasing demand across many markets.

Highlights and key features of the study

Global Silicon Carbide Wafer Laser Slicing Equipment total production and demand, 2021-2032, (Units)

Global Silicon Carbide Wafer Laser Slicing Equipment total production value, 2021-2032, (USD Million)

Global Silicon Carbide Wafer Laser Slicing Equipment production by region & country, production, value, CAGR, 2021-2032, (USD Million) & (Units), (based on production

site)

Global Silicon Carbide Wafer Laser Slicing Equipment consumption by region & country, CAGR, 2021-2032 & (Units)

U.S. VS China: Silicon Carbide Wafer Laser Slicing Equipment domestic production, consumption, key domestic manufacturers and share

Global Silicon Carbide Wafer Laser Slicing Equipment production by manufacturer, production, price, value and market share 2021-2026, (USD Million) & (Units)

Global Silicon Carbide Wafer Laser Slicing Equipment production by Type, production, value, CAGR, 2021-2032, (USD Million) & (Units)

Global Silicon Carbide Wafer Laser Slicing Equipment production by Application, production, value, CAGR, 2021-2032, (USD Million) & (Units)

This report profiles key players in the global Silicon Carbide Wafer Laser Slicing Equipment market based on the following parameters - company overview, production, value, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include DISCO Corporation, 3D-Micromac AG, Synova SA, 4JET Technologies GmbH, Laser Photonics Corporation, E&R Engineering Corporation, Suzhou Delphi Laser Co., Ltd., Guangdong Han's Semiconductor Equipment Technology Co., Ltd., HG Laser Engineering Co., Ltd., Wuhan DR Laser Technology Corp., Ltd., etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World Silicon Carbide Wafer Laser Slicing Equipment market

Detailed Segmentation:

Each section contains quantitative market data including market by value (US\$ Millions), volume (production, consumption) & (Units) and average price (K US\$/Unit) by manufacturer, by Type, and by Application. Data is given for the years 2021-2032 by year with 2025 as the base year, 2026 as the estimate year, and 2027-2032 as the forecast year.

Global Silicon Carbide Wafer Laser Slicing Equipment Market, By Region:

United States

China

Europe

Japan

South Korea

ASEAN

India

Rest of World

Global Silicon Carbide Wafer Laser Slicing Equipment Market, Segmentation by Type:

Single-wafer SiC Laser Slicing Equipment

SiC Wafer Laser Dicing Equipment

Global Silicon Carbide Wafer Laser Slicing Equipment Market, Segmentation by Laser Source Type:

Internal Laser Modification Slicing Equipment

Laser Ablation Cutting Equipment

Thermal Laser Separation Equipment

Global Silicon Carbide Wafer Laser Slicing Equipment Market, Segmentation by Wafer Size:

Up to 4 Inch SiC Wafer Laser Slicing Equipment

Up to 6 Inch SiC Wafer Laser Slicing Equipment

Up to 8 Inch SiC Wafer Laser Slicing Equipment

Up to 12 Inch SiC Wafer Laser Slicing Equipment

Above 12 Inch SiC Wafer Laser Slicing Equipment

Global Silicon Carbide Wafer Laser Slicing Equipment Market, Segmentation by Application:

Electric Vehicle Power Electronics

Renewable Energy Power Conversion

Industrial Power Supplies and Motor Drives

Rail Transit Power Electronics

RF Communications and Radar

Companies Profiled:

DISCO Corporation

3D-Micromac AG

Synova SA

4JET Technologies GmbH

Laser Photonics Corporation

E&R Engineering Corporation

Suzhou Delphi Laser Co., Ltd.

Guangdong Han's Semiconductor Equipment Technology Co., Ltd.

HG Laser Engineering Co., Ltd.

Wuhan DR Laser Technology Corp., Ltd.

Jiangsu Himalaya Semiconductor Co., Ltd.

Westlake Instruments (Hangzhou) Technology Co., Ltd.

Beijing Jingfei Semiconductor Technology Co., Ltd.

Key Questions Answered:

1. How big is the global Silicon Carbide Wafer Laser Slicing Equipment market?
2. What is the demand of the global Silicon Carbide Wafer Laser Slicing Equipment market?
3. What is the year over year growth of the global Silicon Carbide Wafer Laser Slicing Equipment market?
4. What is the production and production value of the global Silicon Carbide Wafer Laser Slicing Equipment market?
5. Who are the key producers in the global Silicon Carbide Wafer Laser Slicing Equipment market?
6. What are the growth factors driving the market demand?

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